



SOT619-18

plastic, thermally enhanced very thin quad flat non-leaded package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 0.85 mm body

1 March 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN48
Package type industry code	HVQFN48
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	12-01-2016
Manufacturer package code	98ASA00719D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	7	-	mm
package width	-	7	-	mm
seated height	0.8	0.85	0.9	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	48	-	



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2 Package outline

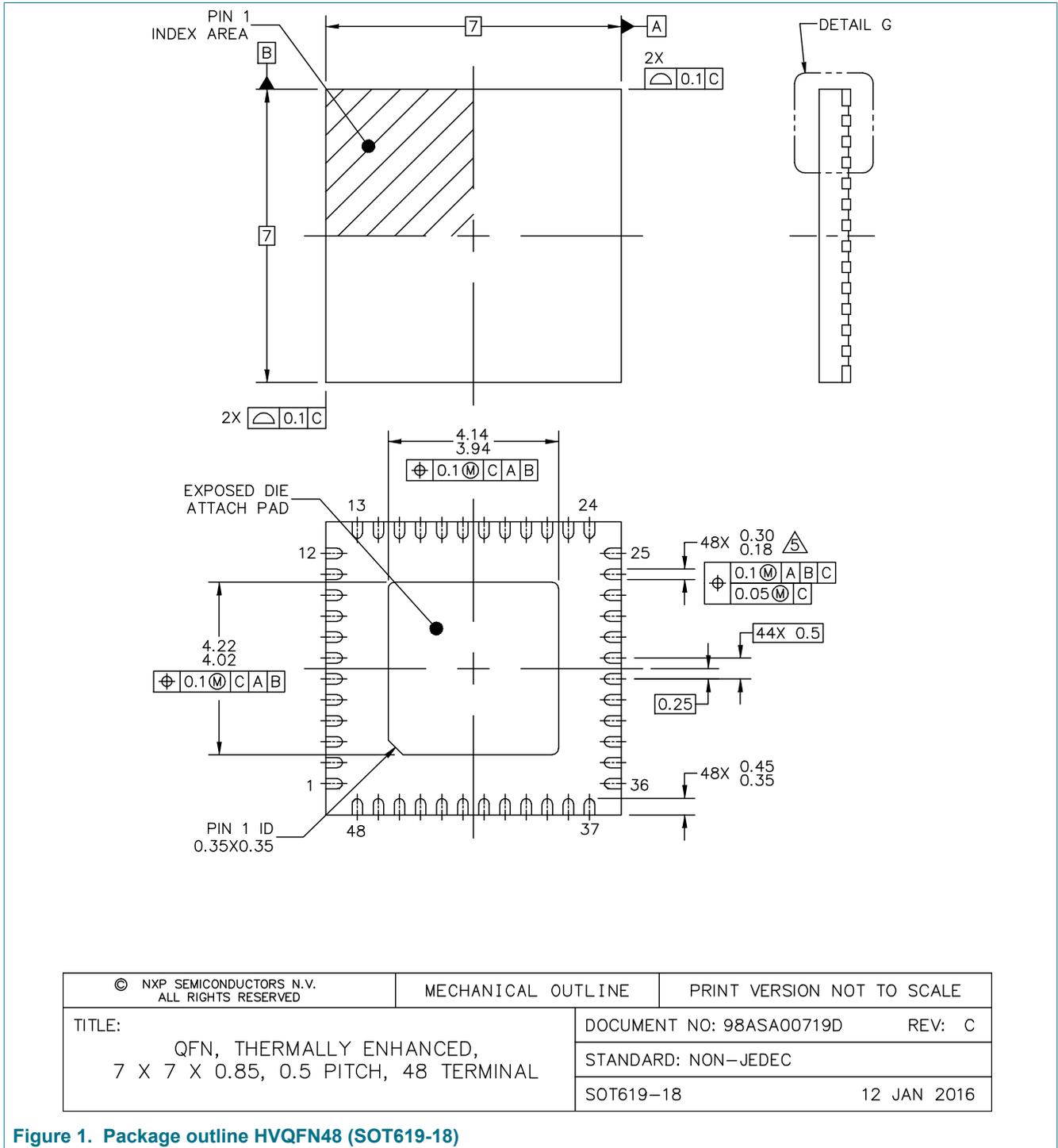


Figure 1. Package outline HVQFN48 (SOT619-18)

plastic, thermally enhanced very thin quad flat non-leaded package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 0.85 mm body

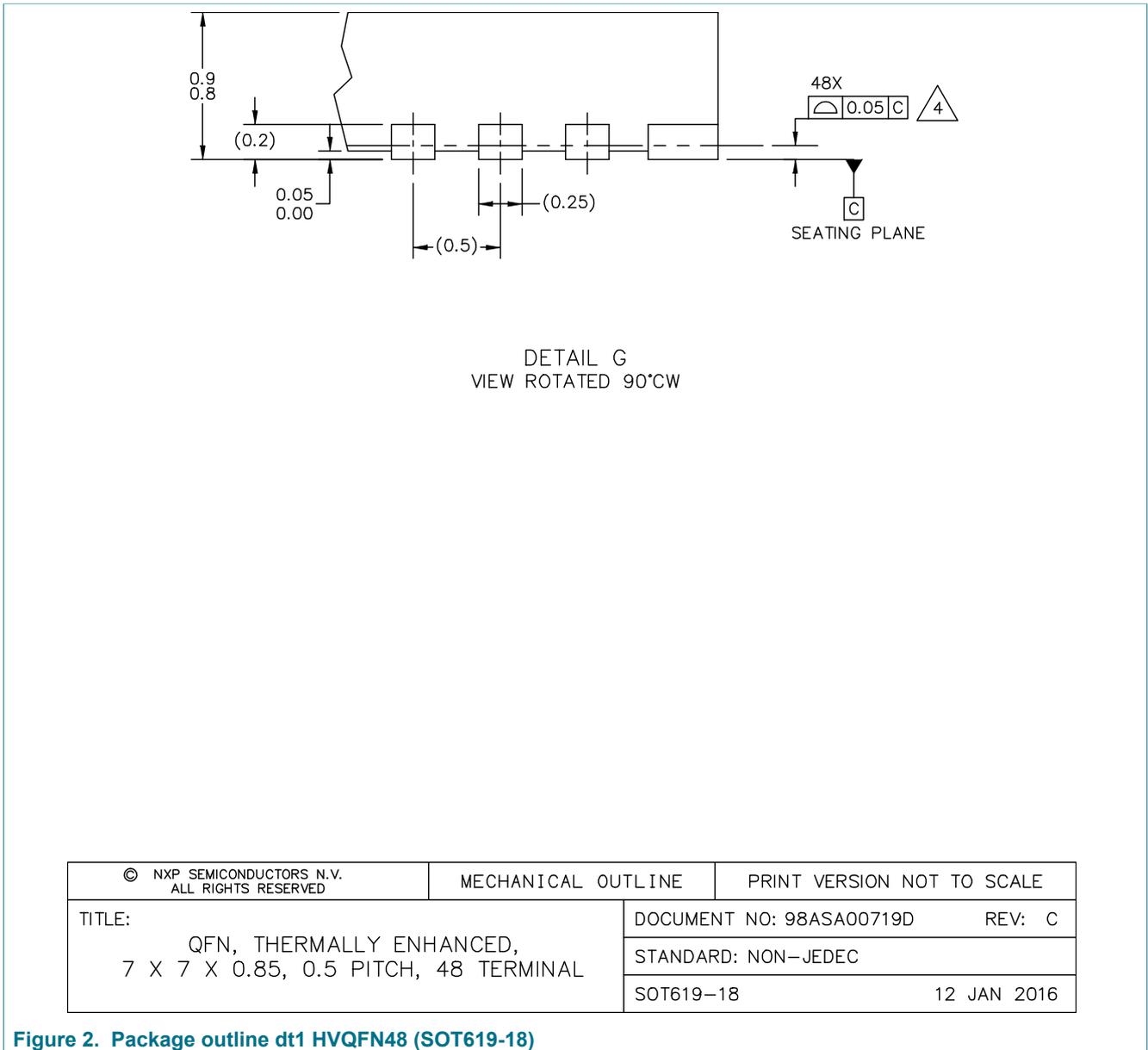


Figure 2. Package outline dt1 HVQFN48 (SOT619-18)

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NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. THIS IS A NON-JEDEC REGISTERED PACKAGE.

⚠ COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.

⚠ DIMENSION APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.3 MM FROM TERMINAL TIP. IF THE TERMINAL HAS THE OPTIONAL RADIUS ON THE OTHER END OF THE TERMINAL, THE DIMENSION SHOULD NOT BE MEASURED IN THAT RADIUS AREA.

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TITLE: QFN, THERMALLY ENHANCED, 7 X 7 X 0.85, 0.5 PITCH, 48 TERMINAL		DOCUMENT NO: 98ASA00719D	REV: C
		STANDARD: NON-JEDEC	
		SOT619-18	12 JAN 2016

Figure 3. Package outline note HVQFN48 (SOT619-18)

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3 Legal information

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